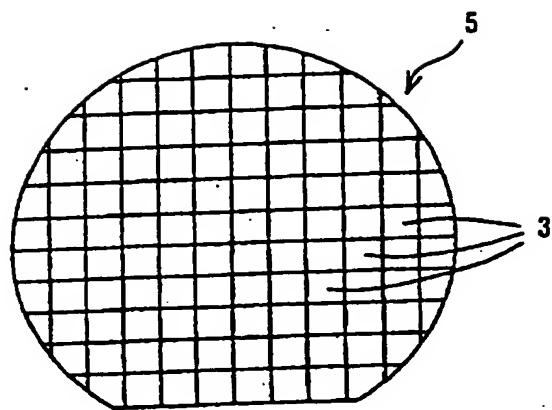
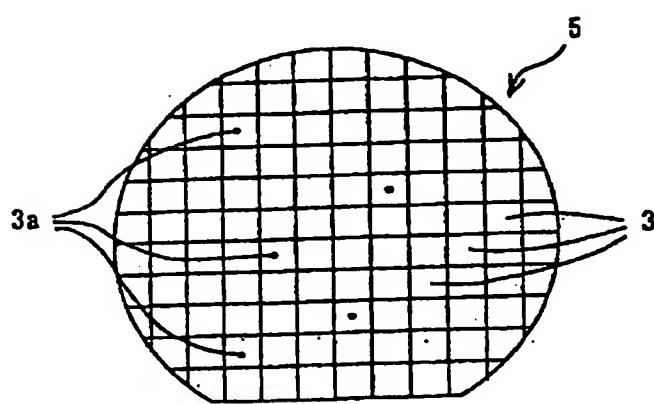


Fig. 1



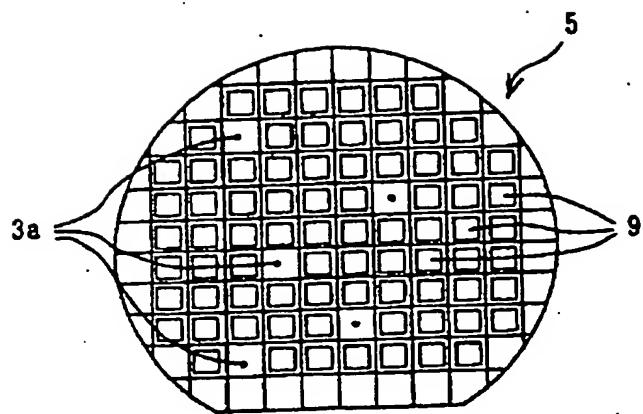
3: Semiconductor chip forming section
5: Semiconductor wafer

Fig. 2



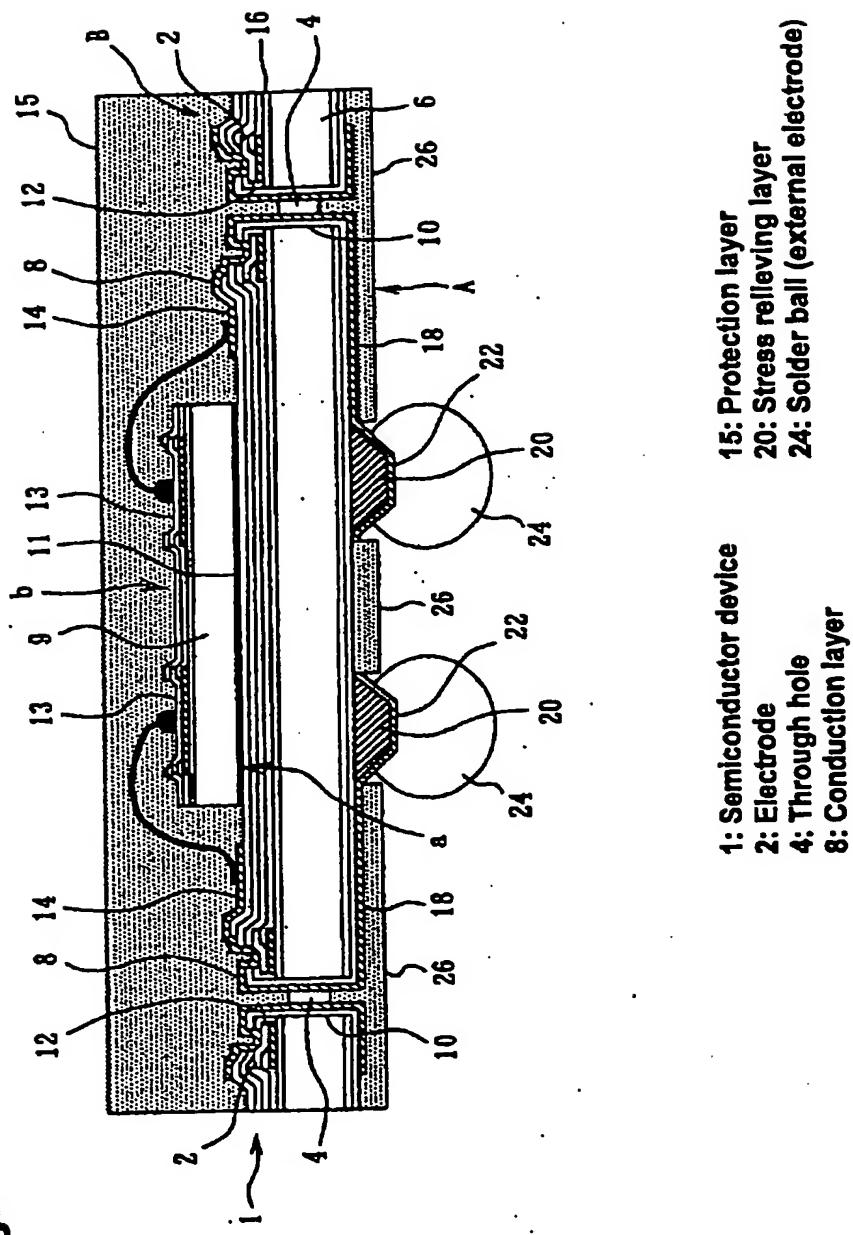
3a: "BAD" mark

Fig. 3



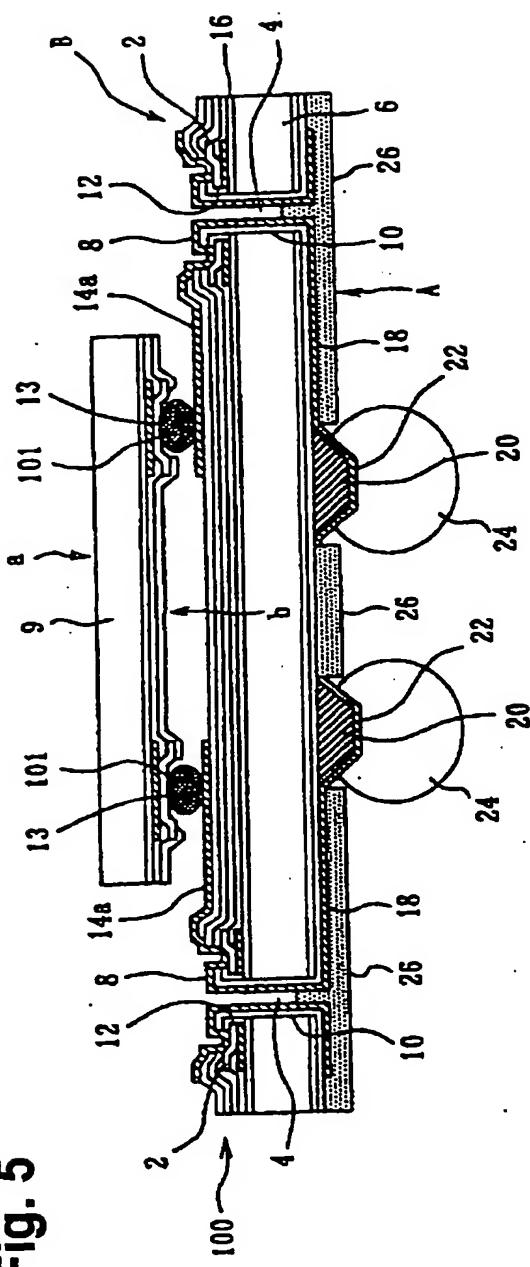
9: Segmented other semiconductor chips

Fig. 4



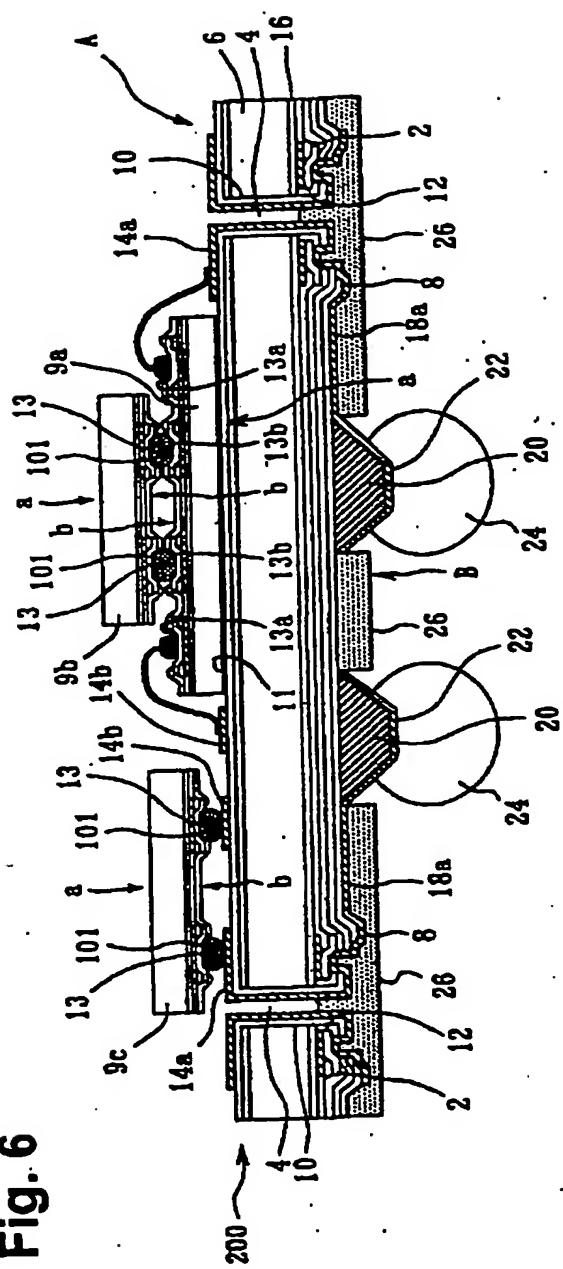
1: Semiconductor device
2: Electrode
4: Through hole
8: Conduction layer
10: Contact
12: Protection layer
13: Stress relieving layer
14: Solder ball
15: Protection layer
16: Solder ball
18: Contact
20: Solder ball (external electrode)
22: Contact
24: Solder ball
26: Contact

Fig. 5



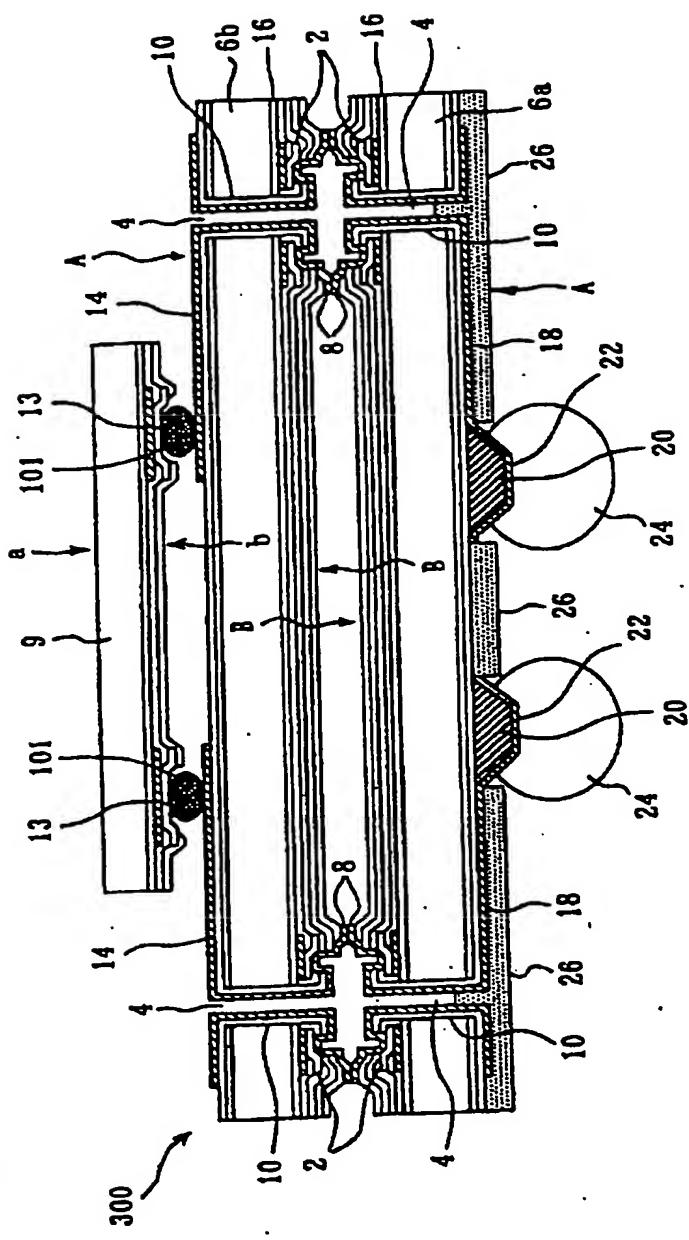
100: Semiconductor device

Fig. 6



9a, 9b, 9c : Segmented other semiconductor chips
200 : Semiconductor device

Fig. 7



6b: Segmented another semiconductor chip
300 : Semiconductor device

Fig. 8

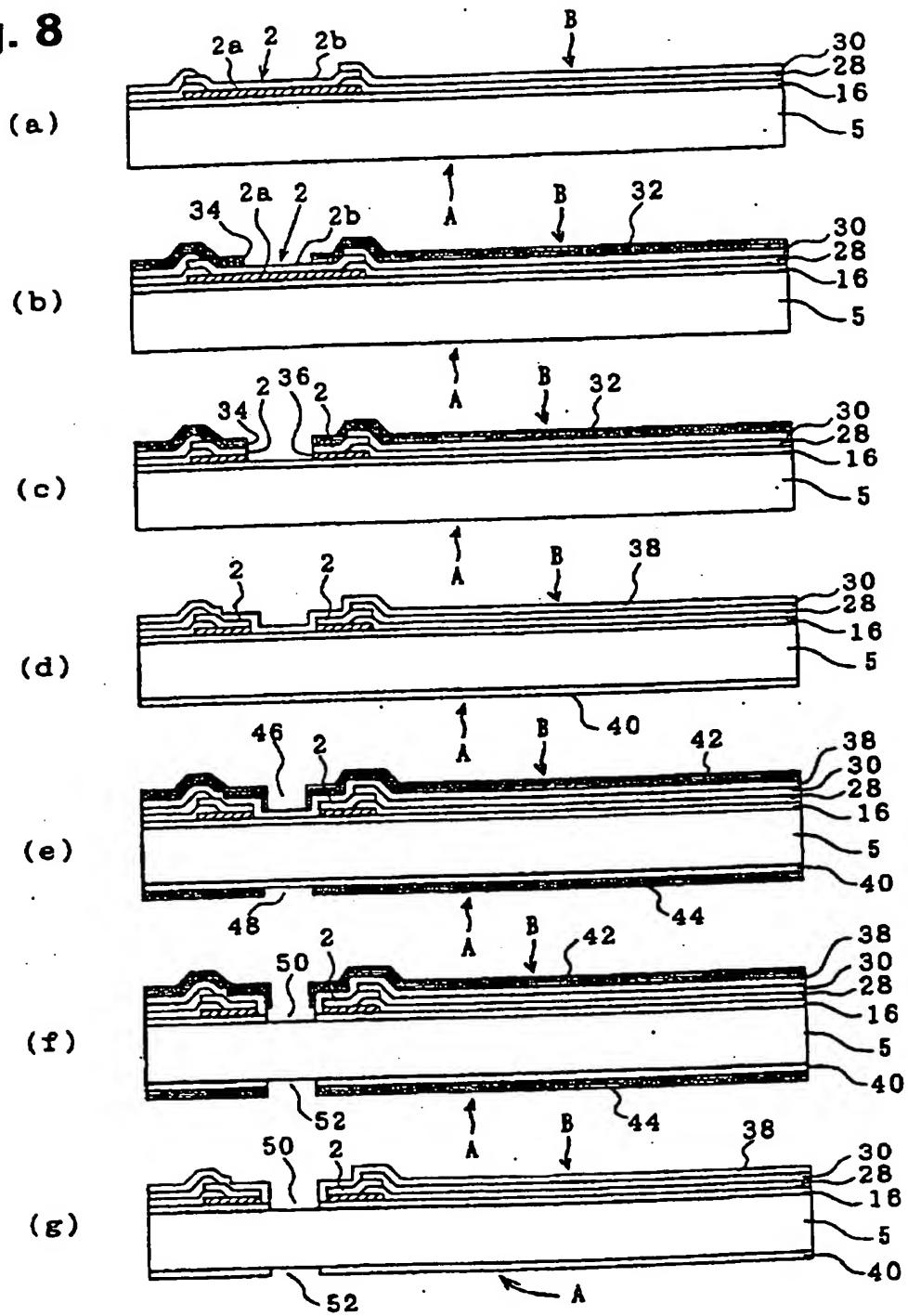


Fig. 9

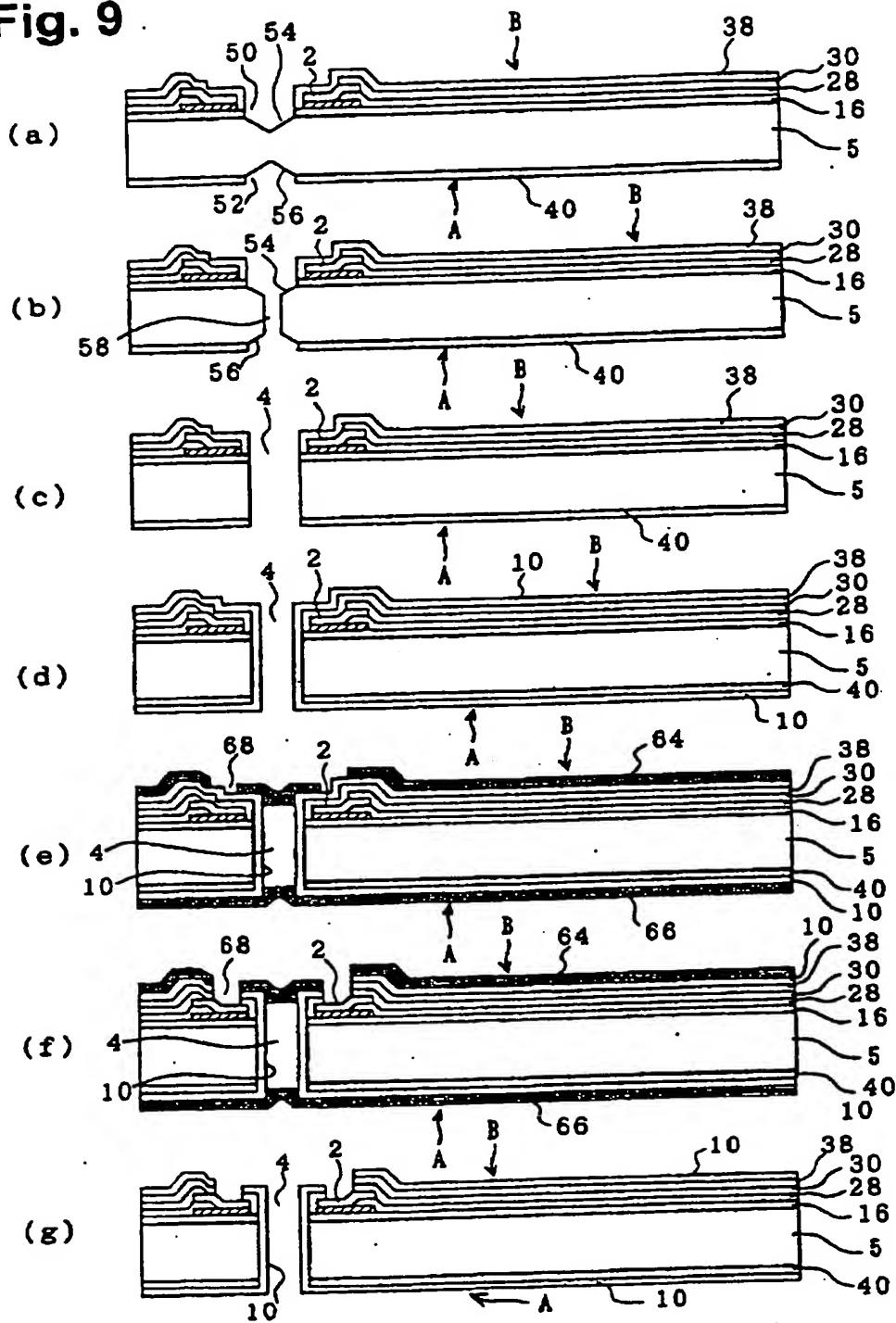


Fig. 10

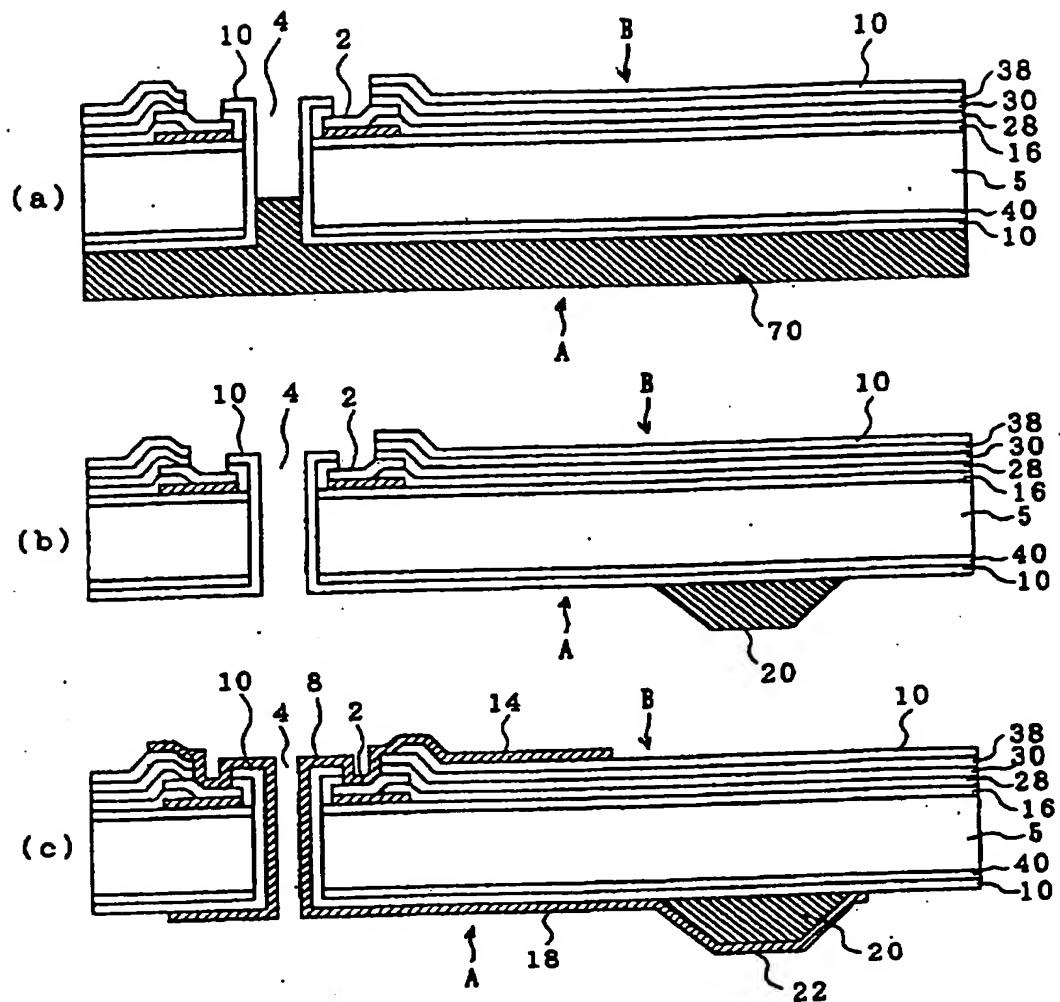


Fig. 11

